Special Issue

Integrated Sensing and Transducing Devices

Message from the Guest Editor

The world today is different from the past. Due to the rapid progress of integrated circuits and advanced processes in the past decade, people's lives have greatly benefited from integrating many miniaturized sensing components and systems. This Special Issue hopes to attract experts in relevant fields to join and present their latest research progress to the world with this theme. The topic includes but is not limited to:

- Lab-on-chip;
- Novel sensing techniques and algorithms;
- Cutting-edge transducing devices;
- Al-based un-met needs to improve micromachining technology for miniaturized sensing components and systems;
- New sensing and transducing applications stemming from advanced processes in device implementation;
- Signal analysis combined with integrated sensing and transducing:
- Circuits and systems for sensing and transducing.

Guest Editor

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Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

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